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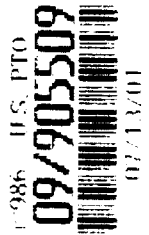
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July 13, 2001

**VIA EXPRESS MAIL NO. EL 676012566 US**

Assistant Commissioner for Patents  
Box Assignments  
Washington, D.C. 20231

Re: Argonne National Laboratory/  
The University of Chicago  
Case No. 218  
New Patent Application For:  
FABRICATION OF HIGH TEMPERATURE  
SUPERCONDUCTORS  
Inventors: Uthamalingam Balachandran et al.

Sir:

09/905509

Please record the attached original document or copy thereof.

## 1. Name of conveying party(ies):

Uthamalingam Balachandran, Stephen E. Dorris,  
Beihai Ma and Meiya Li

## 2. Name and address of receiving party(ies):

The University of Chicago  
5801 South Ellis Street  
Chicago, Illinois 60637

## 3. Nature of Conveyance:

Patent Application Assignment dated July 11, 2001.

## 4. The enclosed Assignment is being filed together with the patent application, the execution date of which is July 11, 2001.

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Assistant Commissioner for Patents

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5. Name and address of party to whom correspondence concerning document should be mailed:

Harry M. Levy, Esq.  
Emrich & Dithmar  
Suite 3000, 300 South Wacker Drive  
Chicago, Illinois 60606

6. Total number of applications involved: 1.
7. Total fee enclosed (37 CFR 3.41): \$ 40.00
8. Please charge any additional fees or credit any overpayment to Deposit Account No. 05-1060. A duplicate copy of this letter is enclosed.
9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: \_\_\_\_\_

7/13/01

  
Harry M. Levy

Total Number of Pages Including Cover Sheet: 3

# ASSIGNMENT

We, Uthamalingam Balachandran of Hinsdale, Stephen E. Dorris of LaGrange Park, Beihai Ma of Downers Grove, and Meiya Li of Woodridge, all in the State of Illinois, for good and valuable considerations to us in hand paid, the receipt and sufficiency whereof is hereby acknowledged, have sold, assigned, conveyed and set over, and do hereby sell, assign, convey and set over unto THE UNIVERSITY OF CHICAGO, an Illinois corporation, organized under the laws of the State of Illinois, having a place of business at 5801 South Ellis Avenue, Chicago, Illinois 60637, its successors and assigns, the entire right, title and interest in and to all subject matter invented or designed by us and disclosed in the patent application for the FABRICATION OF HIGH TEMPERATURE SUPERCONDUCTORS, executed by us on the date hereinafter set forth, and any divisions and continuations thereof and in and to all Letters Patent of the United States, including any reissues and extensions thereof that may be obtained therefor, and the right, where such right can be legally exercised, in its own name to apply for and obtain Letters Patent, Inventor's Certificates, Utility Models and Designs, in countries foreign to the United States, including the full right to claim for any such application the benefits of the International Convention as fully and entirely as we could have done if the application had been in our names, and the entire interest in any Letters Patent, Inventor's Certificate, Utility Model or Design which may be granted on any such application in such foreign country; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue Letters Patent, Inventors Certificates, Utility Models or Designs, on applications as aforesaid, to issue any and all Letters Patent, Inventor's Certificates, Utility Models and Designs that may be granted for said invention to said UNIVERSITY OF CHICAGO, its successors and assigns.

And for the above-named considerations, we hereby agree that we will without additional compensation but without cost to ourselves, promptly communicate to said UNIVERSITY OF CHICAGO, its successors and assigns, any facts known to us respecting said invention whenever requested, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications for Letters Patent, Inventor's Certificates, Utility Models and Designs and assignments thereof, make all rightful oaths and generally do everything possible to aid said assignee, its successors and assigns, as and when requested by them, in obtaining and enforcing proper Letters Patents, Inventor's Certificate, Utility Model and Design protection for said invention or inventions and improvements, in the United States and in all other countries.

Dated: 7-11-01

Uthamalingam Balachandran

Dated: 7/11/01

Stephen E. Dorris

Dated: 7-11-01

Beihai Ma

Dated: 7-11-01

Meiya Li

STATE OF ILLINOIS           )  
  ) ss  
COUNTY OF DU PAGE       )

On this 11<sup>th</sup> day of July, 2001, before me a Notary Public in and for the County and State aforesaid, appeared the above named persons, who are personally known to me to be the same persons whose names are subscribed to the foregoing instrument, and acknowledged that they executed same instrument as their free and voluntary act and for the uses and purposes therein expressed.

WITNESS my hand and seal the day and year last above given.

Miriam R. Legan  
Notary Public

